PIC INTERNATIONAL CONFERENCE

ANGELTECH

2026 AGENDA

Correct as of 09-May-2025 4:59pm
For the latest version of our agenda, visit picinternational.net

Day 1 - Monday 7th April 2025

18:00 **Pre-conference networking drinks reception**

Day 2 - Tuesday 8th April 2025

08:00	Registration and welcome refreshments
08:50	Housekeeping by Michael Lebby and David Cheskis - Conference Chairs

Optimising materials and architectures to progress PICs

09:00	Germanium Electro-Absorption Modulators: Fast, Compact and Energy-efficient *Presented by Daniel Steckler - IHP Microelectronics*
09:15	UV Photonics and Rare-earth Doped Amplifiers with Sputter-deposited Aluminium Oxide Waveguides *Presented by Dawson Bonneville - University of Twente*
09:30	Two-Photon Grayscale Lithography: An Enabling Technology for Scalable Fabrication of Aligned Micro-Optics *Presented by Tobias Hoose - Nanoscribe*
09:45	IMEC's Agile Photonics Platforms *Presented by Leili Shiramin - imec*
10:00	Photonic Integrated Circuit Packaging *Presented by Liam Moroney - Alter Technology*
10:15	Morning Break
10:55	Comparing PIC Platforms: What's the Best Fit? *Presented by Sam Dale - IDTechEx*
11:10	Structuring and Uniformity Improvement of Thin Film LN and other Waveguide Materials *Presented by Philipp Böttger - scia Systems GmbH*
11:25	Advancing towards 50G PON with Flexible Multi-Tech PICs *Presented by Antonio Teixeira - PICadvanced*
11:40	Industry Ready Photonic Integration using Photonic Wire Bonds & Facet-Attached Micro-Lenses *Presented by Matthias Lauermann - Vanguard Automation*
11:55	The Future Role of Bonding in Photonic Integrated Circuits and Co-Packaged Optics *Presented by Dr. Bernd Dielacher - EV Group*
12:10	Lunch Break

Delivering more data: AI, machine learning and tomorrow's computing

Sponsored by OPTICA

13:40	The Evolving Role of Optics in AI Clusters *Presented by Vlad Kozlov - LightCounting*
13:55	Integrated Neuromorphic Photonics and Optical Computing Accelerators *Presented by Mat?j Hejda - Hewlett Packard Enterprise*
14:10	Accelerating Photonic Design for Next Generation Computing with Multiphysics Simulation *Presented by Dylan McGuire - Ansys*
14:25	Driving Functional Test Closer to the Chip *Presented by Matt Adams - VIAVI Solutions*
14:40	Serving Reliable and Robust Test and Measurement Needs *Presented by Kazuo Yamaguchi - Keysight Technologies*
14:55	Custom PDK Framework for PIC Design and Simulation of Datacenter Interconnects *Presented by Andrzej Po?atynski - VPIphotonics*
15:10	Afternoon Break
15:50	Optical Interconnects for Next Generation of AI Systems *Presented by Ana González - iPronics*
16:05	Modular System Concepts for Photonics Packaging and Testing *Presented by Andon Bano - ficonTEC*
16:20	Breaking the Bottleneck: High-Volume Manufacturing of TFLN PICs for Telecom & Datacom *Presented by Amir Ghadimi - Lightium*
16:35	The Future of Optical Interconnects is 3D Printed Freeform Optics *Presented by Dr. Laura Horan - Vanguard Automation*
16:50	Bridging the gap between PIC Designer and Foundries *Presented by Martin Fiers - Luceda Photonics*
17:05	Thin film lithium niobate: the ideal material for scalable high-performance photonic components and PICs *Presented by Pouya Dianat - Quantum Computing*
17:20	Merging Photonic Design and Test Towards Scalable Product Development *Presented by Iñigo Artundo - VLC Photonics*
17:35	Closing Remarks
18:00	Networking Drinks / Dinner Reception

Day 3 - Wednesday 9th April 2025

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebby and David Cheskis - Conference Chairs

Optimising materials and architectures to progress PICs

09:00 Advancing TFLN PICs to Meet Market Demand and Scale Production
Presented by Hamed Sattari - CCRAFT

09:15 Enabling Increasingly Dense fiber-to-chip Connections in Datacenters
Presented by Benoit Fleury - Corning

09:30 InP PIC Platform and Architectures for Data-Center Applications
Presented by Mehrdad Ziari - Nokia

09:45 What about the PIC Manufacturing Sweet Spot?
Presented by Twan Korthorst - New Origin

10:00 Advanced Photonic Integrated Circuit Testing: APEX Technologies' Solution for Next-Generation Optical Devices
Presented by Marc-Andre Laliberte - APEX Technologies

10:15 Morning Break

10:55 Leveraging Opportunity: Test and Assembly as Fulcrum for Scaling
Presented by Scott Jordan - Physik Instrumente

11:10 Sputtered Thin-Film Aluminum Nitride on Insulator for Integrated Photonics: a Scalable Approach and Application Potential
Presented by Thang Duy Dao - Silicon Austria Labs (SAL)

11:25 Accelerating the Adoption of Advanced Photonic Integrated Circuits Using Design Standardisation in PIC Packaging
ficonTEC, PHIX, imec, and Photonics Foundry

11:55 Lunch Break

Harnessing PICs in healthcare, autonomous vehicles and beyond

Sponsored by PhotonDelta

13:25 Scaling up LiDAR with Silicon Photonics
Presented by François Simoens - SteerLight

13:40 Aluminum Oxide PICs for UV Microscopy and Sensing
Presented by Nicolas Le Thomas - Ghent University

13:55 The Future of PICs in Agrifood, Healthcare & Industrial Sensing
Presented by Peter van Arkel - PhotonDelta

14:10 Silicon Photonics for Enabling Chip-based Solid-state Automotive FMCW LiDAR
Presented by Marcus Dahlem - imec

14:25 SiN PICs for Optical Coherence Tomography
Presented by Rainer Hainberger - AIT Austrian Institute of Technology GmbH

14:40 Industrial BioChemical Detection with On-chip Raman Technology
Presented by Ivan-Lazar Bundalo - InSpek

14:55 Afternoon Break

Advancing quantum 2.0 technologies with PICs

15:35 Advancing Quantum Communications with PICs
Presented by Taofiq K. Paraïso - Toshiba Europe Limited

15:50 How Photonics Can Support Quantum Innovation in Different Applications
Presented by Eric Mounier - Yole Group

16:05 Modular, Fibre-Interconnected Architectures for Photonic Quantum Computers
Presented by Thien-An Nguyen - Orca Computing

16:20 Closing Remarks

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